

MC14555B, MC14556B

Dual Binary to 1-of-4 Decoder/Demultiplexer

The MC14555B and MC14556B are constructed with complementary MOS (CMOS) enhancement mode devices. Each Decoder/Demultiplexer has two select inputs (A and B), an active low Enable input (E), and four mutually exclusive outputs (Q0, Q1, Q2, Q3). The MC14555B has the selected output go to the “high” state, and the MC14556B has the selected output go to the “low” state. Expanded decoding such as binary-to-hexadecimal (1-of-16), etc., can be achieved by using other MC14555B or MC14556B devices.

Applications include code conversion, address decoding, memory selection control, and demultiplexing (using the Enable input as a data input) in digital data transmission systems.

Features

- Diode Protection on All Inputs
- Active High or Active Low Outputs
- Expandable
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- All Outputs Buffered
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

| Parameter | Symbol | Value | Unit |
|---|------------------------------------|----------------------------------|------|
| DC Supply Voltage Range | V _{DD} | -0.5 to +18.0 | V |
| Input or Output Voltage Range (DC or Transient) | V _{in} , V _{out} | -0.5 to V _{DD} + 0.5 | V |
| Input or Output Current (DC or Transient) per Pin | I _{in} , I _{out} | ±10 | mA |
| Power Dissipation, per Package (Note 1) | P _D | 500 | mW |
| Ambient Temperature Range | T _A | -55 to +125 | °C |
| Storage Temperature Range | T _{stg} | -65 to +150 | °C |
| Lead Temperature (8-Second Soldering) | T _L | 260 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic “P and D/DW”
Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range V_{SS} ≤ (V_{in} or V_{out}) ≤ V_{DD}.

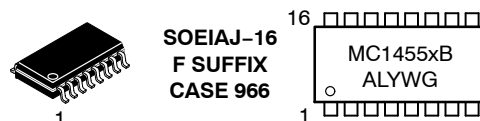
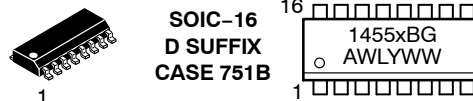
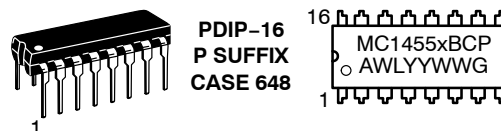
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



ON Semiconductor®

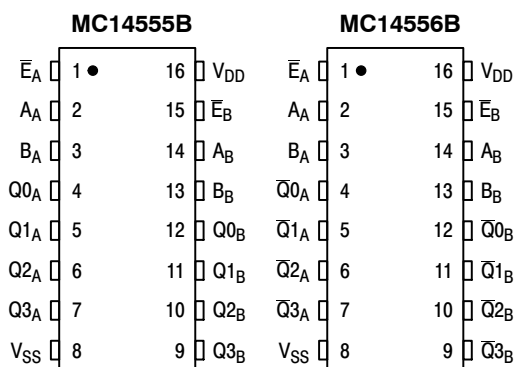
<http://onsemi.com>

MARKING DIAGRAMS



x = 5 or 6
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

PIN ASSIGNMENTS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

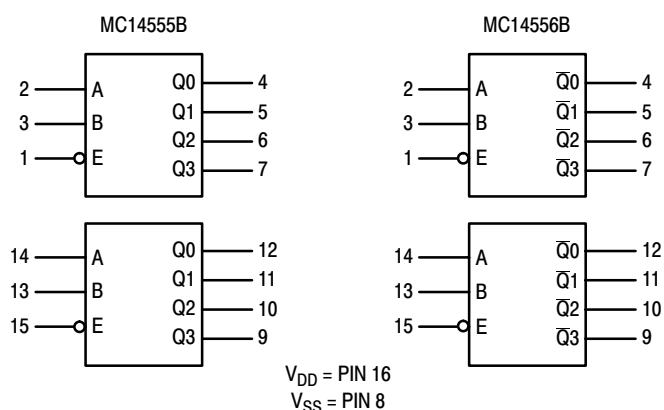
MC14555B, MC14556B

TRUTH TABLE

| Inputs | | | Outputs | | | | | | | |
|-----------|---|--------|----------|----|----|----|------------|------------|------------|------------|
| Enable | | Select | MC14555B | | | | MC14556B | | | |
| \bar{E} | B | A | Q3 | Q2 | Q1 | Q0 | $\bar{Q}3$ | $\bar{Q}2$ | $\bar{Q}1$ | $\bar{Q}0$ |
| 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 0 |
| 0 | 0 | 1 | 0 | 0 | 1 | 0 | 1 | 1 | 0 | 1 |
| 0 | 1 | 0 | 0 | 1 | 0 | 0 | 1 | 0 | 1 | 1 |
| 0 | 1 | 1 | 1 | 0 | 0 | 0 | 0 | 1 | 1 | 1 |
| 1 | X | X | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 1 |

X = Don't Care

BLOCK DIAGRAM



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

| Characteristic | Symbol | V_{DD} Vdc | - 55°C | | 25°C | | | 125°C | | Unit |
|--|-----------------------|-----------------|---|-----------|-------|-----------------|-----------|-------|-----------------|-----------------|
| | | | Min | Max | Min | Typ (Note 2) | Max | Min | Max | |
| Output Voltage $V_{in} = V_{DD}$ or 0 | “0” Level V_{OL} | 5.0 | - | 0.05 | - | 0 | 0.05 | - | 0.05 | Vdc |
| | | 10 | - | 0.05 | - | 0 | 0.05 | - | 0.05 | |
| $V_{in} = 0$ or V_{DD} | “1” Level V_{OH} | 5.0 | 4.95 | - | 4.95 | 5.0 | - | 4.95 | - | Vdc |
| | | 10 | 9.95 | - | 9.95 | 10 | - | 9.95 | - | |
| Input Voltage ($V_O = 4.5$ or 0.5 Vdc) ($V_O = 9.0$ or 1.0 Vdc) ($V_O = 13.5$ or 1.5 Vdc) | “0” Level V_{IL} | 5.0 | - | 1.5 | - | 2.25 | 1.5 | - | 1.5 | Vdc |
| | | 10 | - | 3.0 | - | 4.50 | 3.0 | - | 3.0 | |
| $V_O = 0.5$ or 4.5 Vdc) ($V_O = 1.0$ or 9.0 Vdc) ($V_O = 1.5$ or 13.5 Vdc) | “1” Level V_{IH} | 5.0 | 3.5 | - | 3.5 | 2.75 | - | 3.5 | - | Vdc |
| | | 10 | 7.0 | - | 7.0 | 5.50 | - | 7.0 | - | |
| Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 4.6$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc) | Source I_{OH} | 5.0 | -3.0 | - | -2.4 | -4.2 | - | -1.7 | - | mAdc |
| | | 5.0 | -0.64 | - | -0.51 | -0.88 | - | -0.36 | - | |
| | | 10 | -1.6 | - | -1.3 | -2.25 | - | -0.9 | - | |
| | | 15 | -4.2 | - | -3.4 | -8.8 | - | -2.4 | - | |
| $V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc) | Sink I_{OL} | 5.0 | 0.64 | - | 0.51 | 0.88 | - | 0.36 | - | mAdc |
| | | 10 | 1.6 | - | 1.3 | 2.25 | - | 0.9 | - | |
| | | 15 | 4.2 | - | 3.4 | 8.8 | - | 2.4 | - | |
| Input Current | I_{in} | 15 | - | ± 0.1 | - | ± 0.00001 | ± 0.1 | - | ± 1.0 | μAdc |
| Input Capacitance, ($V_{in} = 0$) | C_{in} | - | - | - | - | 5.0 | 7.5 | - | - | pF |
| Quiescent Current (Per Package) | I_{DD} | 5.0 | - | 5.0 | - | 0.005 | 5.0 | - | 150 | μAdc |
| | | 10 | - | 10 | - | 0.010 | 10 | - | 300 | |
| | | 15 | - | 20 | - | 0.015 | 20 | - | 600 | |
| Total Supply Current (Notes 3, 4) (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs, all buffers switching) | I_T | 5.0 10 15 | $I_T = (0.85 \mu\text{A/kHz}) f + I_{DD}$ $I_T = (1.70 \mu\text{A/kHz}) f + I_{DD}$ $I_T = (2.60 \mu\text{A/kHz}) f + I_{DD}$ | | | | | | μAdc | |

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF: $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) V f k$ where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.002$.

MC14555B, MC14556B

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

| Characteristic | Symbol | V_{DD} | Min | Typ (Note 6) | Max | Unit |
|---|--------------------|-----------------|-------------|-----------------|-------------------|------|
| Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$ | t_{TLH}, t_{THL} | 5.0 10 15 | – – – | 100 50 40 | 200 100 80 | ns |
| Propagation Delay Time – A, B to Output $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 135 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 62 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 45 \text{ ns}$ | t_{PLH}, t_{PHL} | 5.0 10 15 | – – – | 220 95 70 | 440 190 140 | ns |
| Propagation Delay Time – E to Output $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 115 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 52 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 40 \text{ ns}$ | t_{PLH}, t_{PHL} | 5.0 10 15 | – – – | 200 85 65 | 400 170 130 | ns |

- The formulas given are for the typical characteristics only at 25°C .
- Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

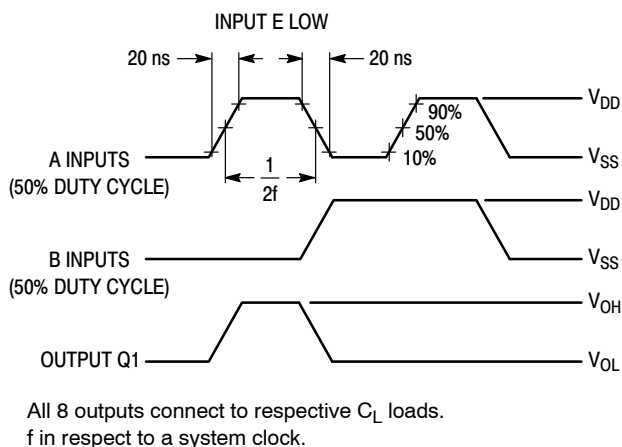


Figure 1. Dynamic Power Dissipation Signal Waveforms

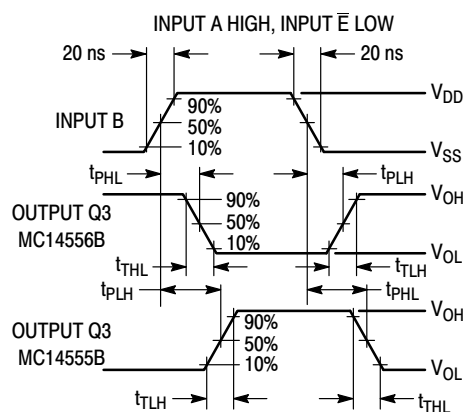
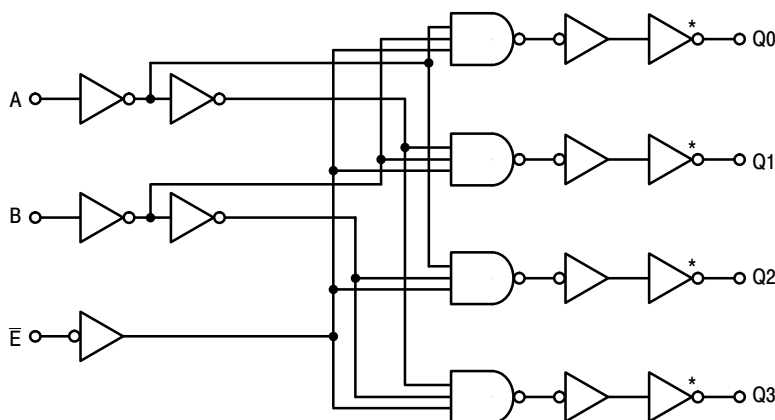


Figure 2. Dynamic Signal Waveforms

LOGIC DIAGRAM (1/2 of Dual)



*Eliminated for MC14555B

MC14555B, MC14556B

ORDERING INFORMATION

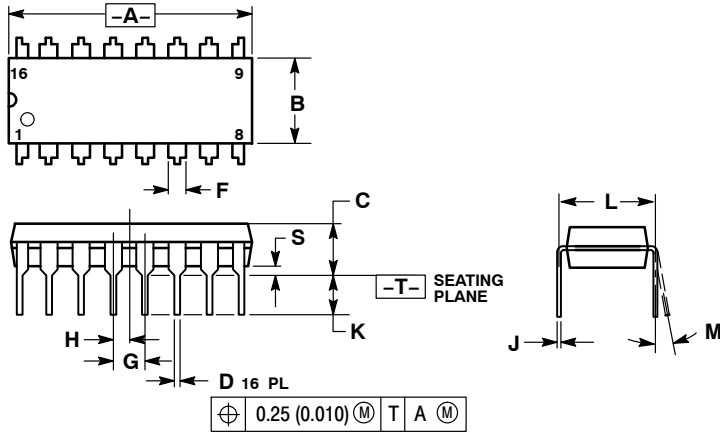
| Device | Package | Shipping† |
|--------------|------------------------|--------------------|
| MC14555BCPG | PDIP-16 (Pb-Free) | 500 Units / Rail |
| MC14555BDG | SOIC-16 (Pb-Free) | 48 Units / Rail |
| MC14555BDR2G | SOIC-16 (Pb-Free) | 2500 / Tape & Reel |
| MC14555BFELG | SOEIAJ-16 (Pb-Free) | 2000 / Tape & Reel |
| MC14556BCPG | PDIP-16 (Pb-Free) | 500 Units / Rail |
| MC14556BDR2G | SOIC-16 (Pb-Free) | 2500 / Tape & Reel |
| MC14556BFELG | SOEIAJ-16 (Pb-Free) | 2000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MC14555B, MC14556B

PACKAGE DIMENSIONS

PDIP-16
CASE 648-08
ISSUE T

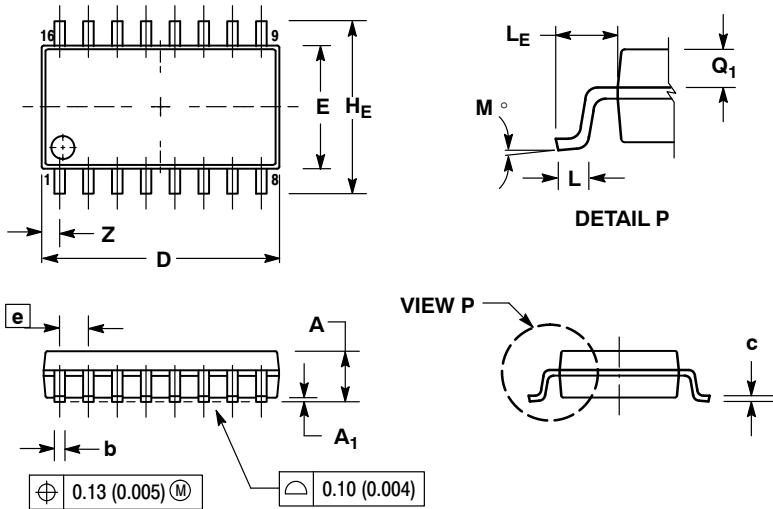


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.740 | 0.770 | 18.80 | 19.55 |
| B | 0.250 | 0.270 | 6.35 | 6.85 |
| C | 0.145 | 0.175 | 3.69 | 4.44 |
| D | 0.015 | 0.021 | 0.39 | 0.53 |
| F | 0.040 | 0.70 | 1.02 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| H | 0.050 BSC | | 1.27 BSC | |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.130 | 2.80 | 3.30 |
| L | 0.295 | 0.305 | 7.50 | 7.74 |
| M | 0° | 10° | 0° | 10° |
| S | 0.020 | 0.040 | 0.51 | 1.01 |

SOEIAJ-16
CASE 966-01
ISSUE A



NOTES:

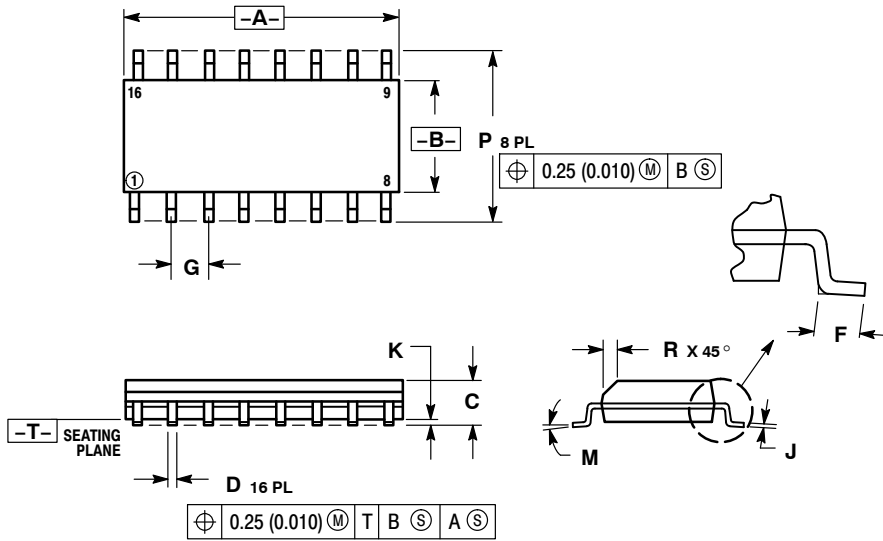
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| DIM | MILLIMETERS | | INCHES | |
|----------------|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | --- | 2.05 | --- | 0.081 |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.10 | 0.20 | 0.007 | 0.011 |
| D | 9.90 | 10.50 | 0.390 | 0.413 |
| E | 5.10 | 5.45 | 0.201 | 0.215 |
| e | 1.27 BSC | | 0.050 BSC | |
| H _E | 7.40 | 8.20 | 0.291 | 0.323 |
| L | 0.50 | 0.85 | 0.020 | 0.033 |
| L _E | 1.10 | 1.50 | 0.043 | 0.059 |
| M | 0° | 10° | 0° | 10° |
| Q ₁ | 0.70 | 0.90 | 0.028 | 0.035 |
| Z | --- | 0.78 | --- | 0.031 |

MC14555B, MC14556B

PACKAGE DIMENSIONS

SOIC-16
CASE 751B-05
ISSUE K

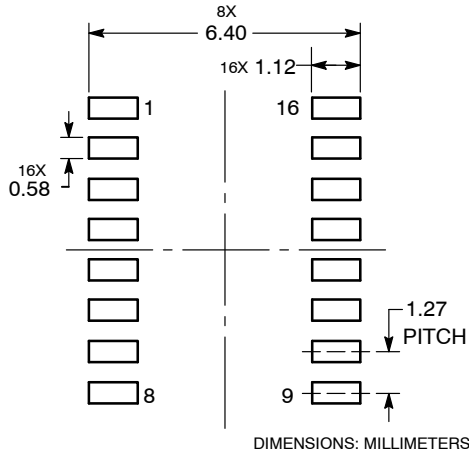


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 9.80 | 10.00 | 0.386 | 0.393 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 BSC | | 0.050 BSC | |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° 7° | | 0° 7° | |
| P | 5.80 | 6.20 | 0.229 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

SOLDERING FOOTPRINT



ON Semiconductor and **ON** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local Sales Representative

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru